

# SILICON PHOTONICS

Dries Van Thourhout / 24 October 2018 / SPICE workshop Mainz



UNIVERSITEIT  
GENT

imec

**Spice**

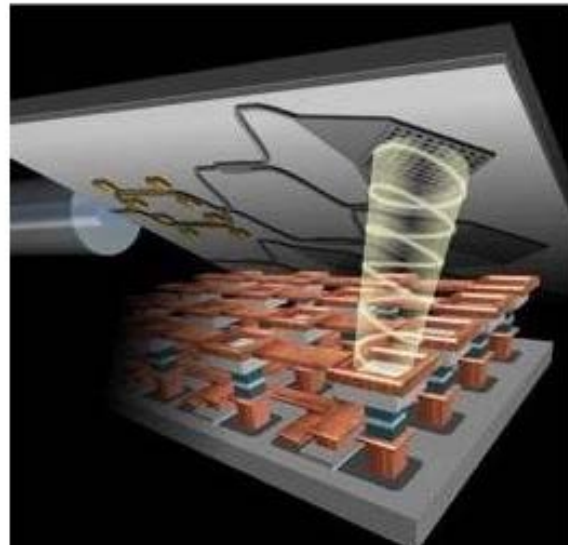
EU H2020 FET-OPEN Project

Objective: developing a **spintronic-photonic IC platform** to create world class ultra fast and low power memory and sensor designs

Silicon Photonics !

Need:

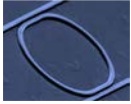
- Distribution of optical signals (passives)
- Switching of optical signals
- Coupling of optical signals



Coordinator: **Martijn Heck** (Aarhus)

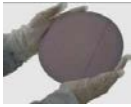
Partners: Aarhus, IMEC, Spintec, Nijmegen, Quantum Wise

# PHOTONICS RESEARCH GROUP



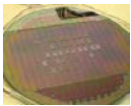
## Research Group of Ghent University

- Faculty of Engineering and Architecture
- Department of Information Technology (INTEC)
- Associated laboratory of IMEC
- Member of the Center for Nano- & Biophotonics (NB photonics)



## Technology Research

- Photonic Integration: Systems on a chip
- On silicon: "Silicon Photonics"
- Enhanced with new materials: III-V, ferro-electrics, graphene, ...



## Applications

- High-speed telecom and datacom
- Sensing for life sciences: visible and Mid-IR
- Optical information processing



9 Professors  
 16 postdocs  
 50 PhD students  
 10 support staff

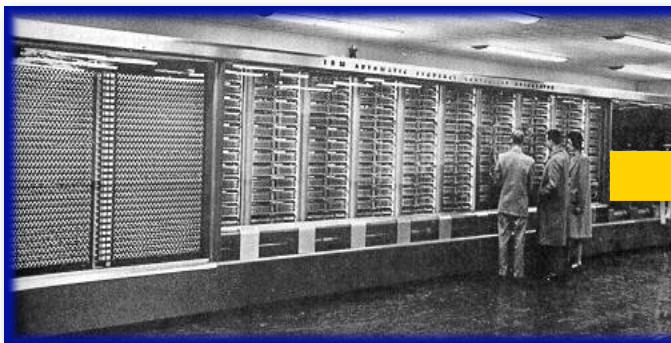
20+ nationalities  
 6 ERC grants  
 4 spin-off companies  
 50 journal papers/year  
 Class 100 clean rooms



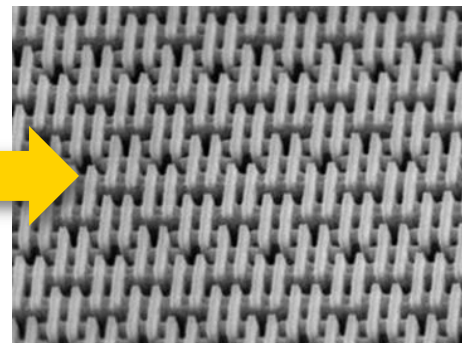
Associated lab of imec  
 Europe's Largest Research Centre in Nanoelectronics

# WHY INTEGRATED PHOTONICS ?

- In electronics: integration leads to miniaturization, higher performance, cost savings, robustness



IBM, mark 1  
 5 tons of components  
 can multiply in 1 sec



Modern TSMC-chip (7nm)  
 Several billion transistors  
 billions of multiplications per sec  
 (from TSMC.com)



## WHY NOT INTEGRATED PHOTONICS ?

### Electronics

- Single building block:
  - Transistor
- Single material:
  - Silicon
- Relaxed processing requirements
  - Digital devices
  - High yield
- Massive economies of scale
- Common roadmap



### Photonics

- Many building blocks
  - Laser, Modulator, Detector Filter
- Many technologies and materials
  - Laser : III-V semiconductors
  - Modulator : LiNbO3
  - Filter : Glass, Polymers
- High processing requirements
  - Analog devices
  - Low Yield
- No economies of scale advantage
- Many faction pushing own solution

## CAN “SILICON PHOTONICS” OVERCOME THIS BOTTLENECK ?

- Single material platform
  - Silicon transparent at telecom wavelengths
  - Very high contrast : compact circuits
  - Detectors (germanium), Modulators (pn-junction)
  - Wafer level testing
- Reuse installed equipment base
  - Use best equipment available
  - Without the capital expense ...
  - Possibility to ramp up to high volumes
- Some standardization and roadmapping ongoing

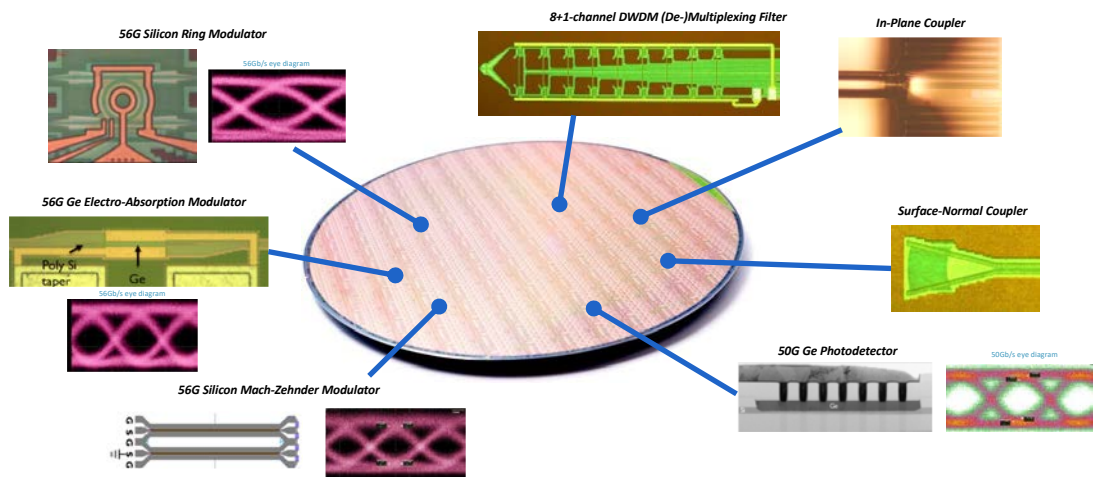


## THE PAST 5-10 YEARS: STUNNING INDUSTRIAL DEVELOPMENT IN SILICON PHOTONICS FOR TELECOM AND DATACOM

- active optical cables (eg PSM4: 4x28 Gb/s on parallel fibers)
- WDM transceivers (eg 4 WDM channels x 25 Gb/s on single fiber)
- coherent receiver (eg 100 Gb/s PM-QPSK)
- fiber-to-the-home bidirectional transceiver (eg 12 x 2.5 Gb/s)
- monolithic receiver (eg 16x20Gb/s)
- 40Gb/s, 50Gb/s and 100 Gb/s Ethernet (future: 400Gb/s)
- ...



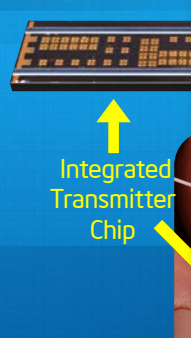
## IMEC SILICON PHOTONICS PLATFORM FULLY INTEGRATED 8X50G DWDM SI PHOTONICS TECHNOLOGY



Co-integration of the various building blocks in a single platform (O-band, C-band)  
 Today available on 200mm wafer size, coming soon on 300mm  
 95% compatible with CMOS130 in commercial foundries



### The 5G I... Transmitting a...



Transmit Module

## Luxtera Product Assembly at CM Site in Asia

**Comparison of 130nm CMOS Photonic**

Others (Announced)

- 130nm design rules for
- 130nm design rules for
- CMOS FEOL integrat (Ge-last after activat)
- Large Litho variations required
- 6mm<sup>2</sup> per transceiver

10x higher inte


The only ame

50channels x

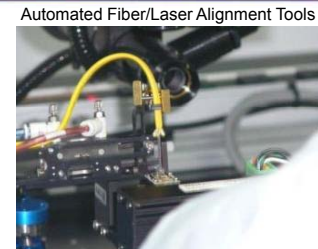
(can be

<http://www.research...>


**Module (Cable End) Assembly Line**




**Automated Fiber/Laser Alignment Tools**



**Test Stations & Housing Assembly stations**



**Shipping Production Volumes**



Luxtera is producing silicon photonics solutions in high-volume

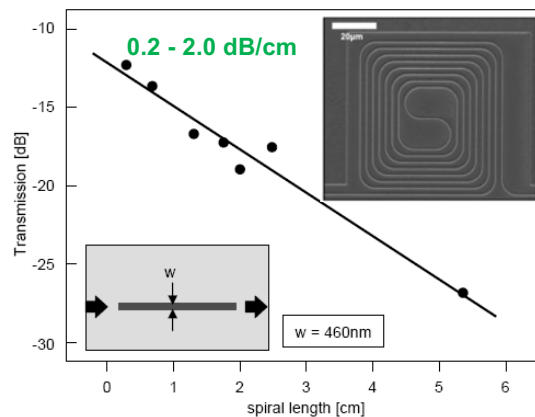
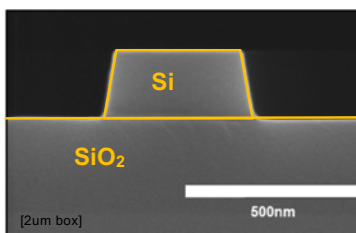
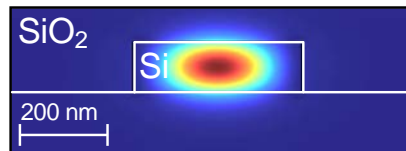
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GHENT UNIVERSITY **imec**

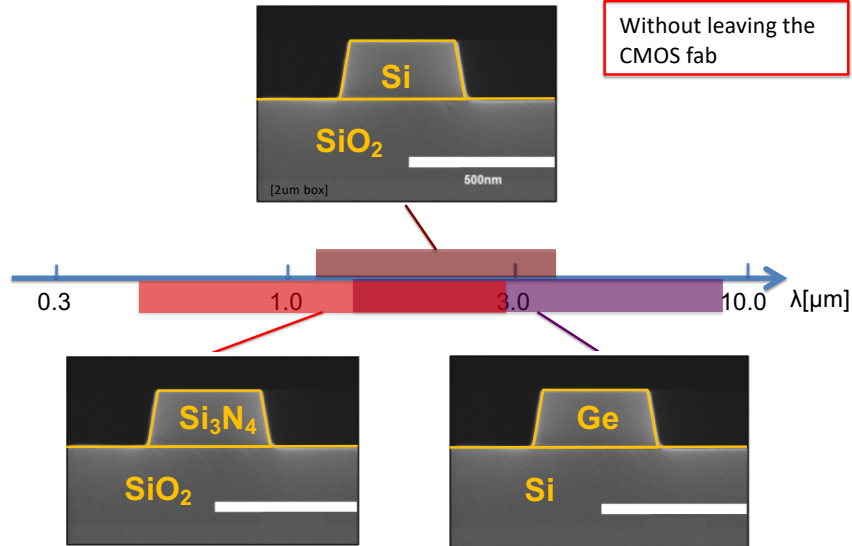
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## STRAIGHT WAVEGUIDE

- Our standard waveguide: 450nm x 220nm Si
- Fabricated using 193nm DUV lithography
- In standard pilot line, on 200mm or 300mm wafer
- Starting from SOI or amorphous silicon



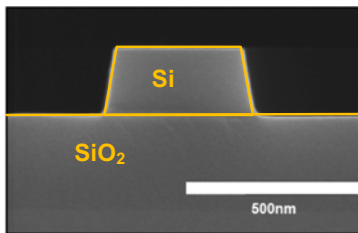
### SILICON PHOTONICS: EXTENDING THE WAVELENGTH RANGE



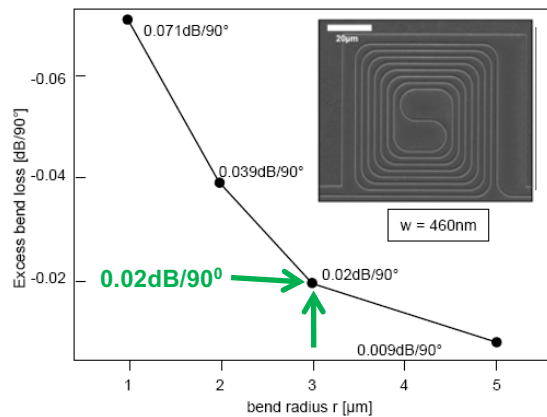
### BEND WAVEGUIDE

S.K. Selvaraja, JLT 27, p.4070 (2009)  
 Y. A. Vlasov and S. J. McNab, Optics Express, p. 1622 (2004)

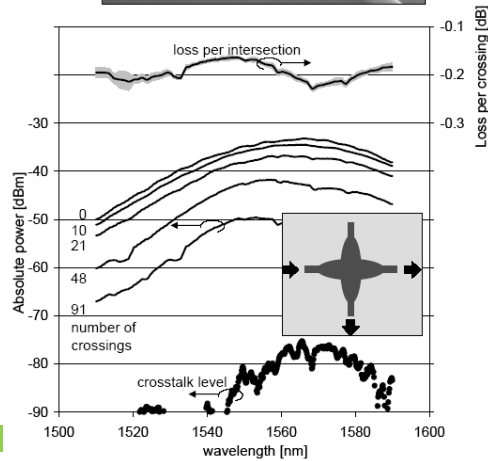
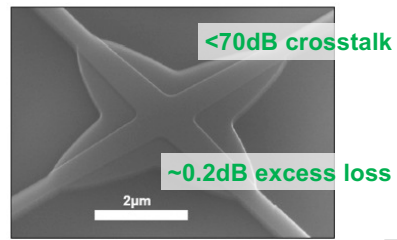
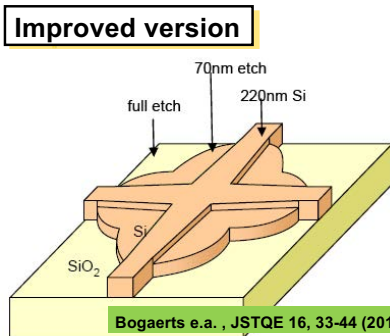
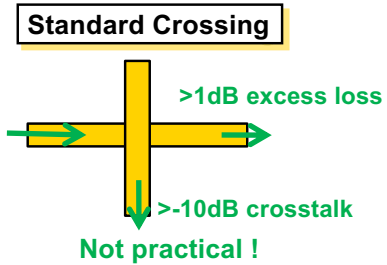
- Our standard waveguide: 450nm x 220nm Si
- Fabricated using 193nm DUV lithography
- In standard pilot line, on 200mm wafer
- Starting from SOI or amorphous silicon



- In agreement with FDTD calculations
- Offset straight-bend might improve performance (?)



## CROSSINGS

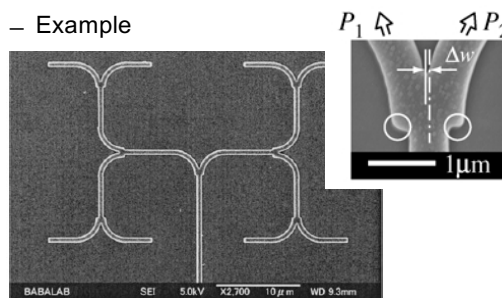


## THE Y-JUNCTION

(a)		2.0 dB
(b)		0.5 dB
(c)		0.5 dB
(d)		< 0.1 dB
(e)		0.3 dB
(f)		< 0.1 dB

Large losses for standard Y-junction  
Need improved design !!!

– Example



- Experiment: 0.3dB excess loss
- Some imbalance due to opt. prox. effects

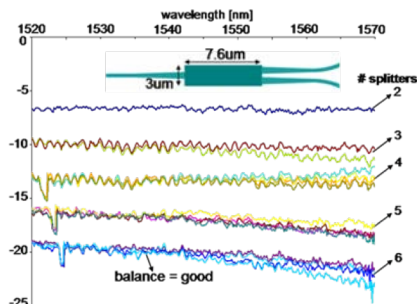
Sakai e.a., IEICE Trans E85-C 1033 (2002)

Fukazawa e.a. Jpn JAP 41, p L1461 (2002)



## MULTI-MODE INTERFEROMETER (MMI)

### Standard MMI splitter



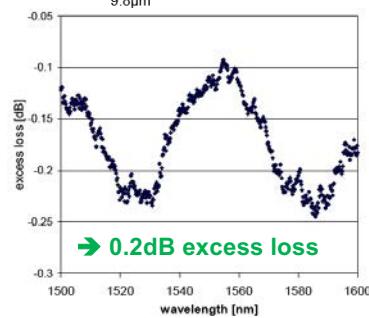
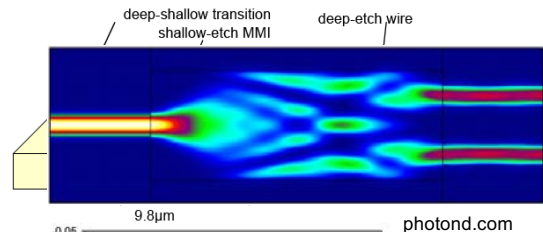
→ 0.3dB excess loss

Bogaerts e.a., JSTQE 16, 33-44 (2010)

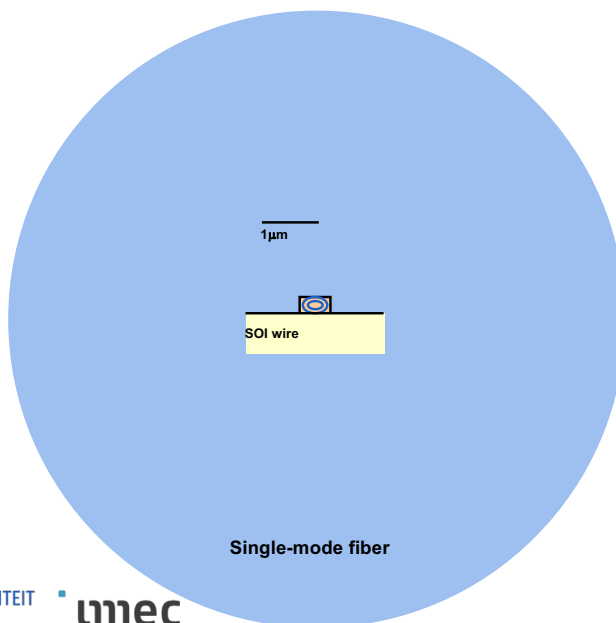
IME A\*STAR paper, PTL (2013)



### Improved version



## FIBER - CHIP COUPLING



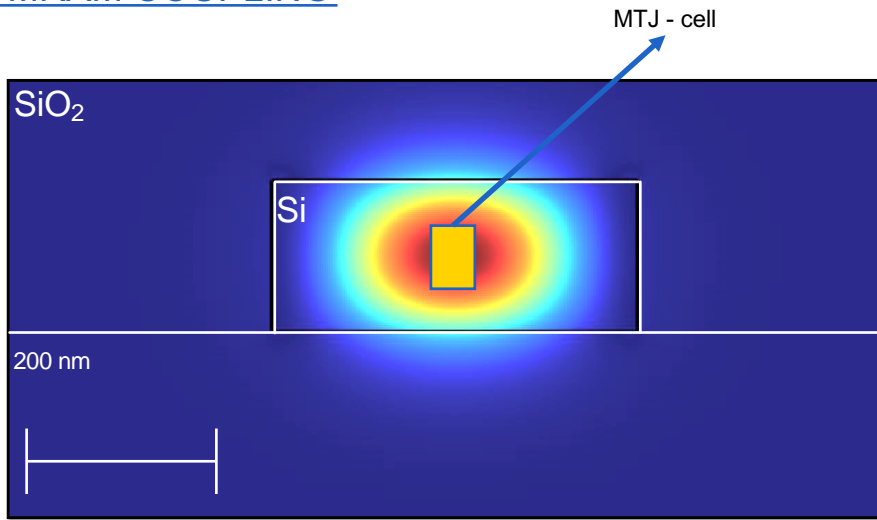
We would like

- Low loss
- Broadband
- High coupling tolerance
- No facet reflections
- Waferscale testability
- Easy to fabricate
- A solution for the polarization problem

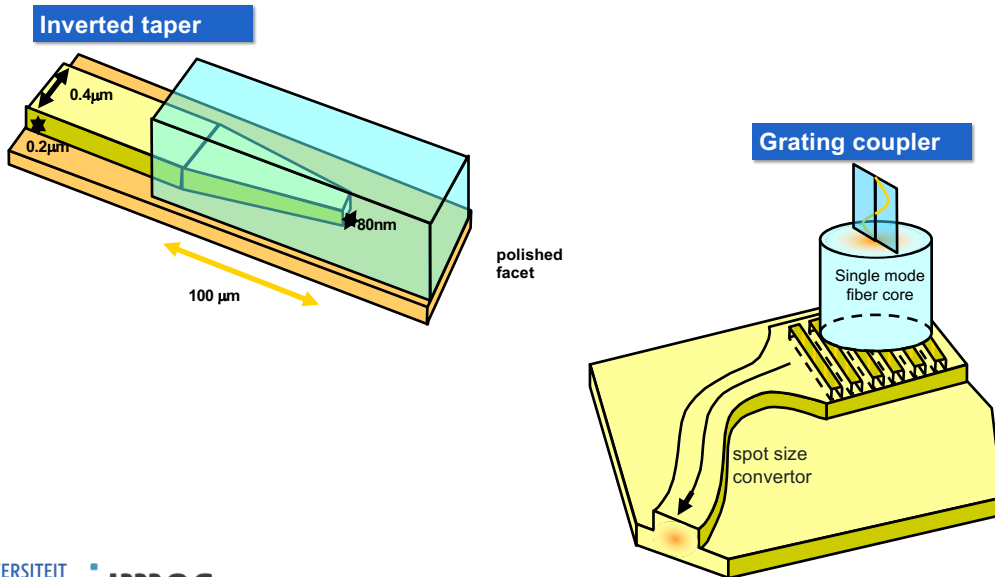




### CHIP - MRAM COUPLING

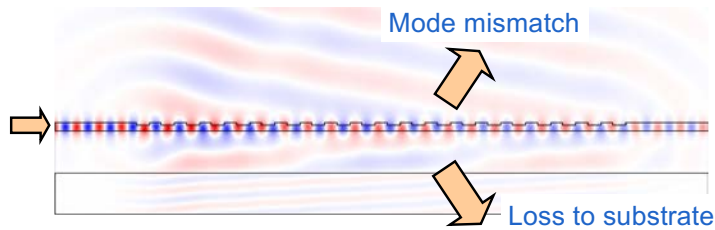


### FIBER CHIP COUPLING: TWO WIDELY USED SOLUTIONS

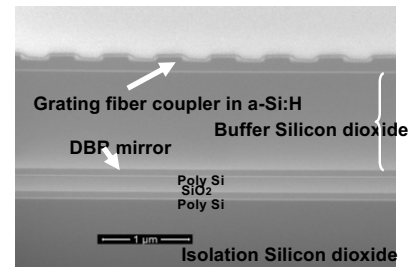
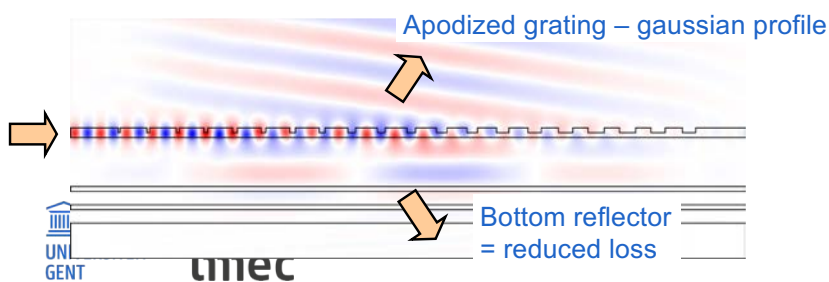


## GRATING COUPLER – OPERATING PRINCIPLE

– Standard coupler (33% efficiency)

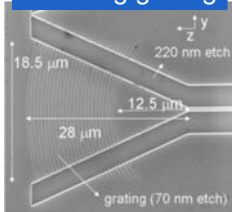


– Improved coupler (>90% efficiency)



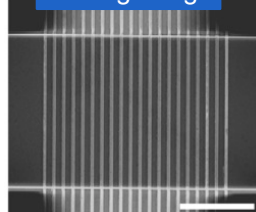
## GRATING ZOO

Focusing grating



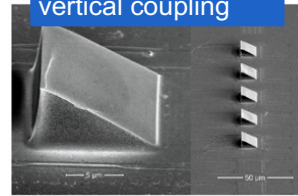
F. Van Laere, PTL 19, p. 1919 (2006)

Metal gratings



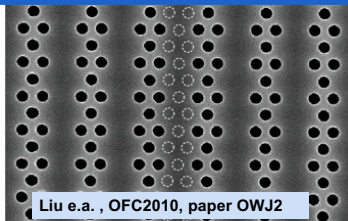
Scheerlinck, APL 92 p.031104 (2008)

Polymer wedge for vertical coupling



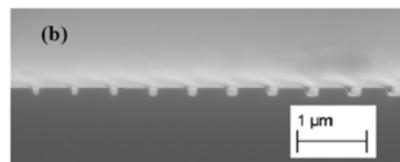
Schrauwen e.a. Phot. West, 7218, p.72180B (2009)

Photonic crystal grating for low reflection deep etch



Liu e.a., OFC2010, paper OWJ2

Apodized grating



Tang e.a., OFC2010, paper OWJ6

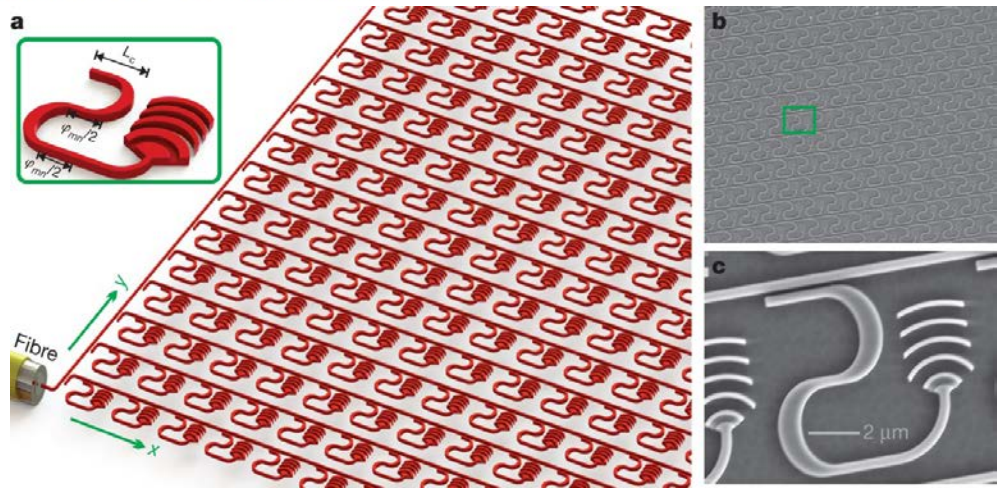
## Large-scale nanophotonic phased array

Jie Sun, Erman Timurdogan, Ami Yaacobi, Ehsan Shah Hosseini & Michael R. Watts

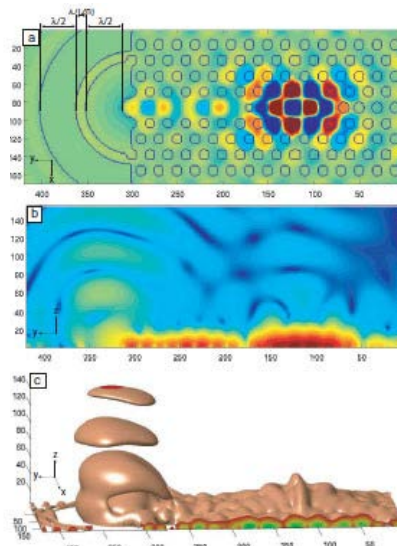
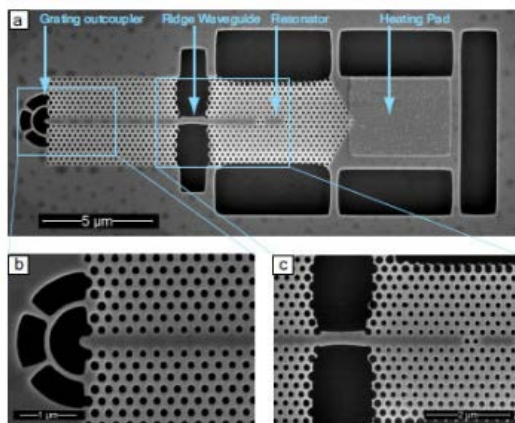
Affiliations | Contributions | Corresponding author

Nature 493, 195–199 (10 January 2013) | doi:10.1038/nature11727

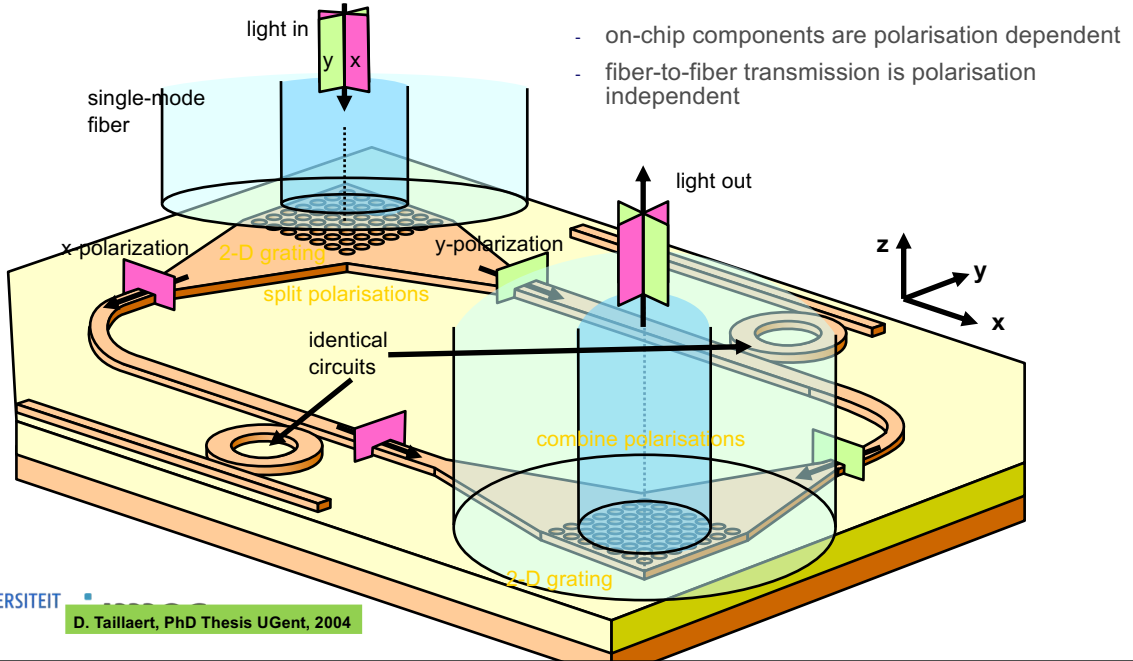
Received 02 August 2012 | Accepted 29 October 2012 | Published online 09 January 2013



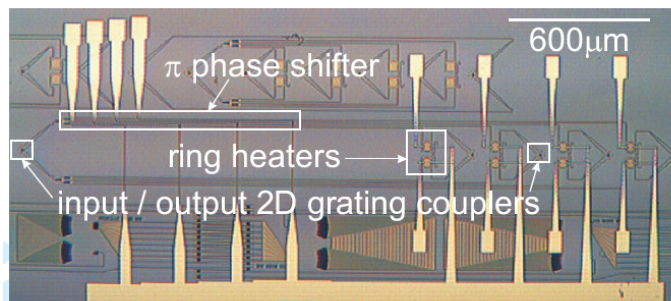
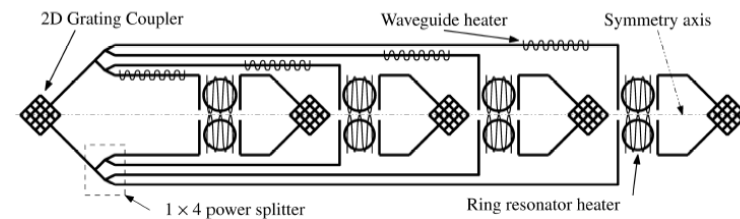
## MINIMIZING THE OUTPUT COUPLER



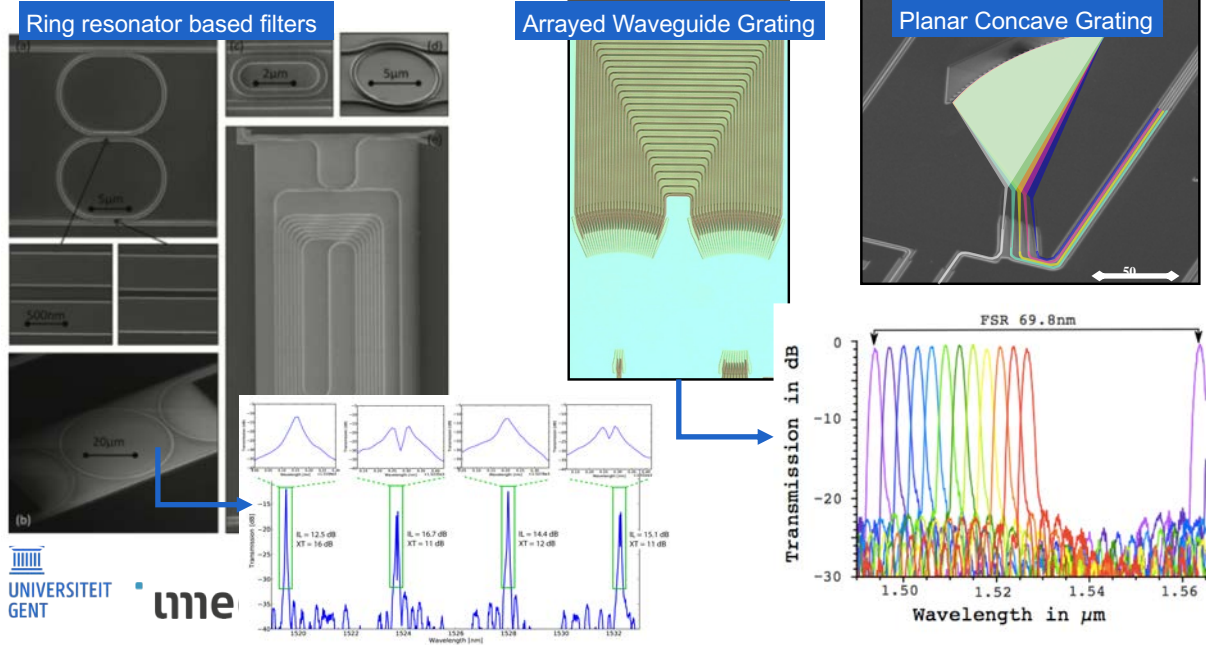
## POLARISATION DIVERSITY CIRCUIT



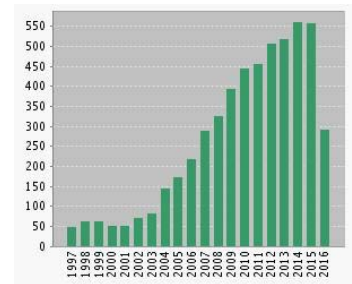
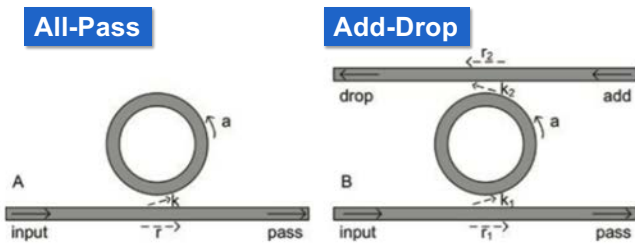
## 2D-GRATING COUPLERS ALLOW CONTROL OF POLARIZATION



# LARGE FAMILY OF PASSIVE DEVICES



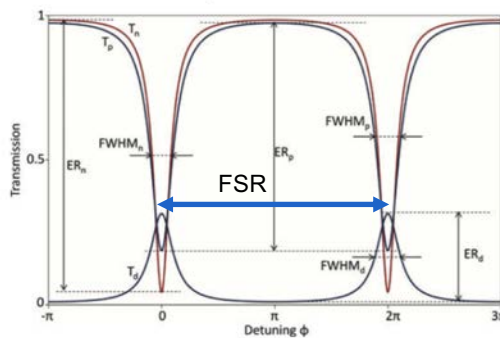
## RING RESONATORS



### Main characteristics

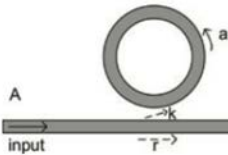
- Resonance wavelength
- Free Spectral Range (Periodicity)
- Quality Factor  $Q$  ( $Q = \lambda / \Delta\lambda$ )
- Finesse
- Loss ...

$Q=1E3 \rightarrow \Delta\lambda=1.5\text{nm}$   
 $Q=1E6 \rightarrow \Delta\lambda=1.5\text{pm}$

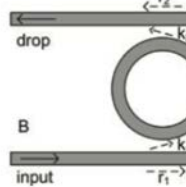


# RING RESONATORS

## All-Pass



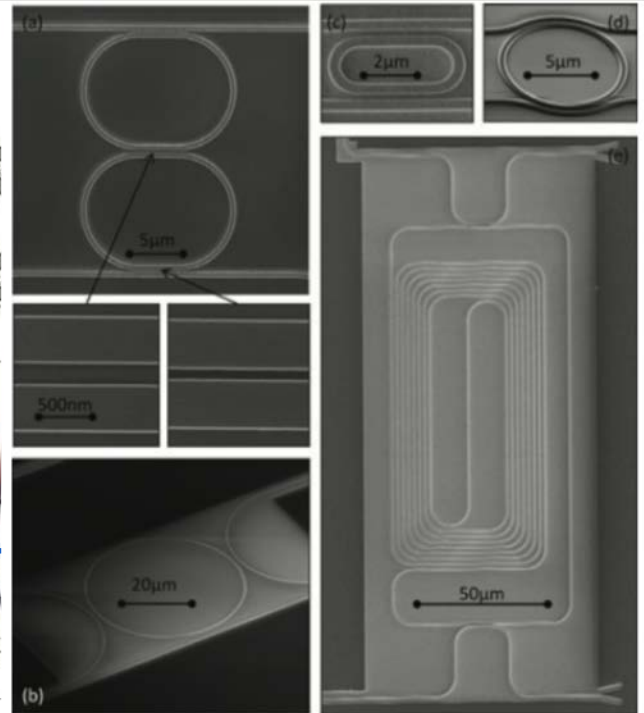
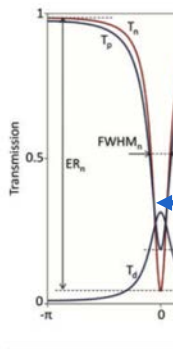
## Add-Drop



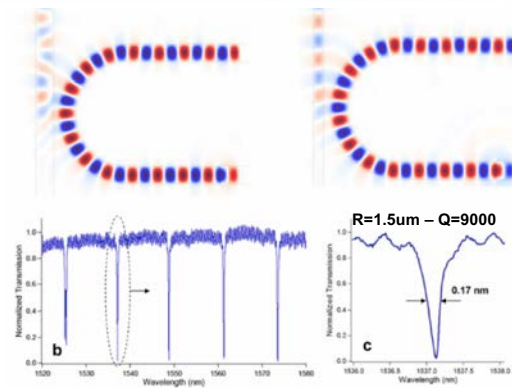
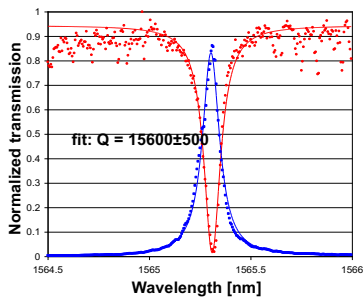
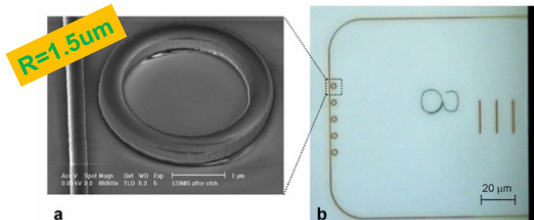
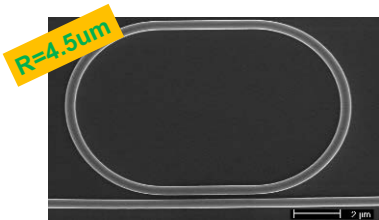
### Main characteristics

- Resonance wavelength
- Free Spectral Range (Periodicity)
- Quality Factor  $Q$  ( $Q = \lambda / \Delta\lambda$ )
- Finesse
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$Q=1E3 \rightarrow \Delta\lambda=1.5\text{nm}$   
 $Q=1E6 \rightarrow \Delta\lambda=1.5\text{pm}$



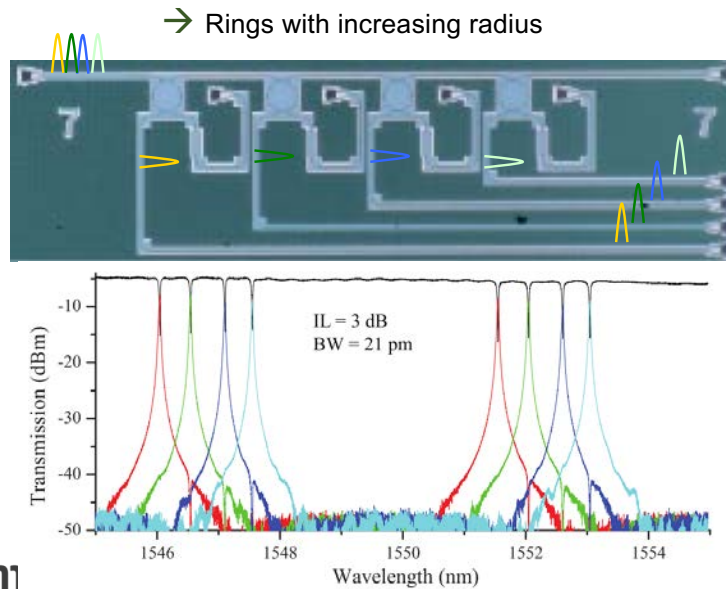
# RING RESONATORS



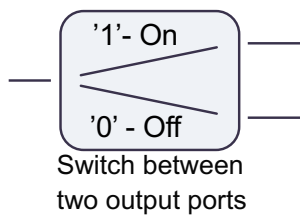
Bogaerts e.a., JSTQE 16, 33-44 (2010)

Xu e.a., OE 16, pp 4309 (2008)

## THE RING RESONATOR AS WAVELENGTH DEMULTIPLEXER



## SI PHOTONICS PLATFORM – SWITCHING TECHNOLOGIES

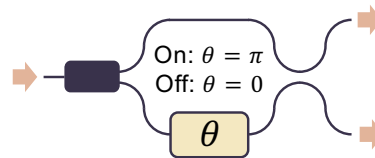


$\theta$  Optical phase shift

$$\Delta\theta = (2\pi/\lambda)\Delta nL$$

Refractive index change required!!

MZI-based switch

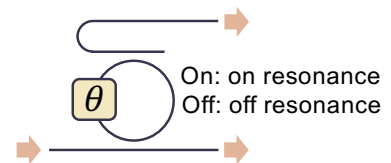


+ Bandwidth (10s of nm)  
- Efficiency ( $\sim$ mW)

J. Van Campenhout, OpEx 17, p23793 (2009)

A. Ribeiro, OpEx 25, p29779 (2017)

Ring-resonator-based switch



+ Efficiency ( $\sim$  $\mu$ W)  
- Bandwidth ( $<$ 1 nm)

Q. Xu, OpEx 15, p430 (2007)

N. Sherwood-Droz, OpEx 16, p15915 (2008)



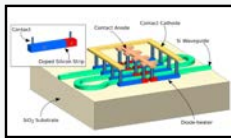
**SI PHOTONICS PLATFORM – REFRACTIVE INDEX CHANGE**

**Electro-Optic effect**

$\Delta n_{\text{LiNbO}_3}/E = 100 \text{ pm/V}$	LiNbO <sub>3</sub>	- Yes
$\Delta n_{\text{strained-Si}}/E = 15 \text{ pm/V}$	Silicon	- No (unless strained)

**Thermo-Optic effect**

$$\Delta n_{\text{Si}}/T = 1.86 \times 10^{-4} \text{ K}^{-1}$$



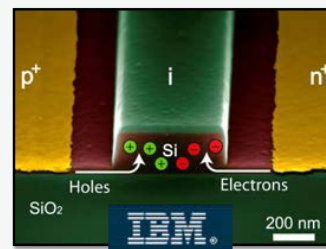
Large in Silicon (2 x LiNbO<sub>3</sub>)  
-> but slow (~100 μs)

**Plasma-Dispersion effect**

$$\Delta n_{\text{Si}}(N) = -8.8 \times 10^{-22} N - 8.5 \times 10^{-18} N^{0.8}$$

$$\alpha(N) = (8.5 \times 10^{-18} + 6 \times 10^{-18}) N$$

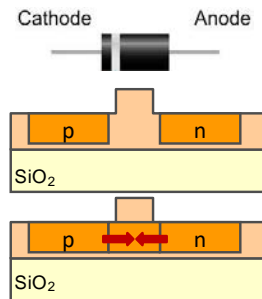
Carrier injection or  
Carrier depletion



**CARRIER INJECTION TECHNOLOGY - CONCEPT**

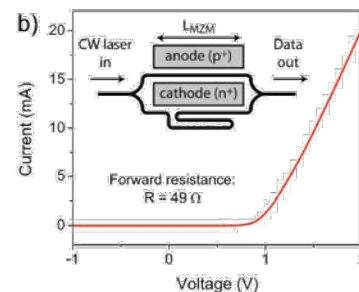
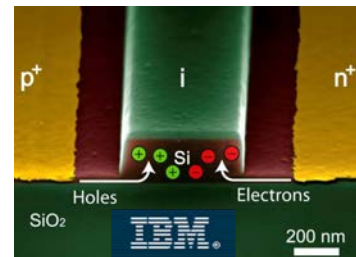
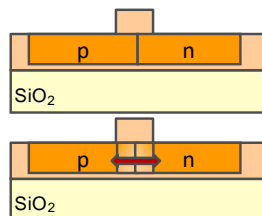
**Carrier injection**

- p-i-n diode in forward bias
- Inject carriers into waveguides
- Strong effect (many carriers)
- Moderate fast effect (~1 GHz)



**Carrier depletion**

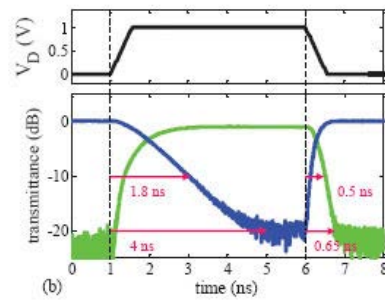
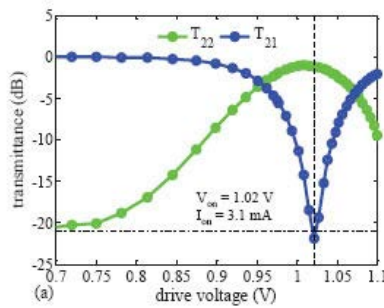
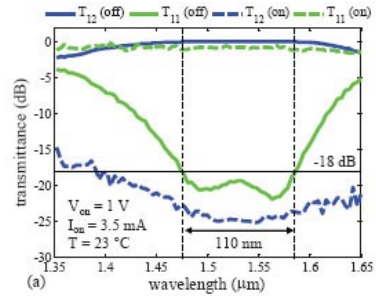
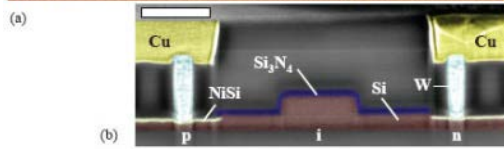
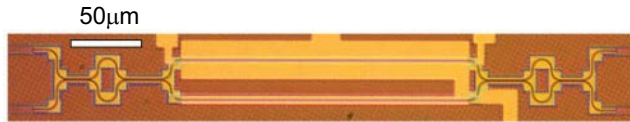
- p-n diode in reverse bias
- Extract carriers from waveguides
- Weaker effect
- Fast effect (>40 GHz)



W. Green, OpEx 15, p17106 (2007)



# A TYPICAL MACH-ZEHNDER PIN SWITCH



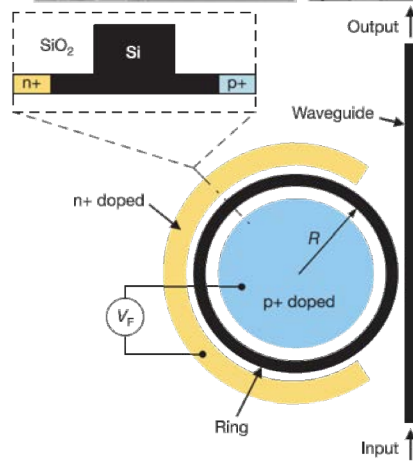
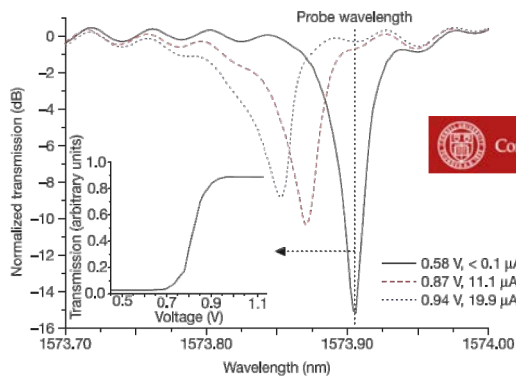
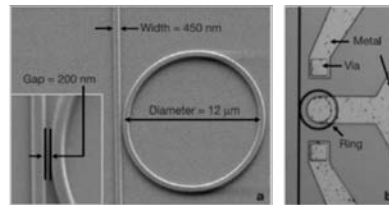
J. Van Campenhout, OpEx 17, p23793 (2009)



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# INJECTION MODULATOR (RING)

- Use resonator to enhance effects
- Speed ~2GB/s
- With pre-emphasis: >20GB/s



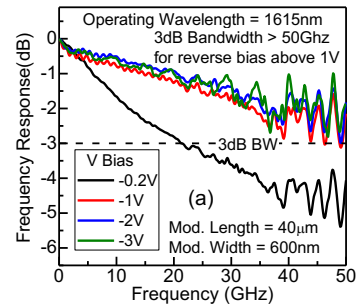
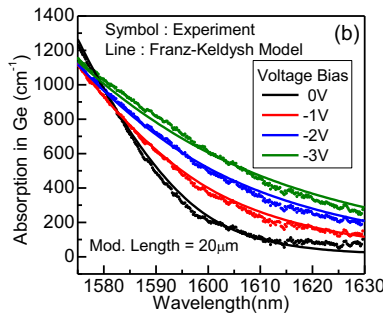
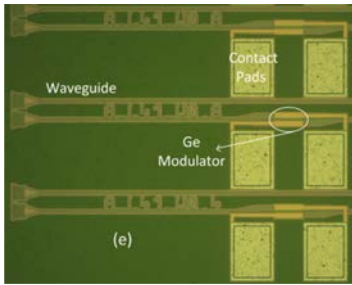
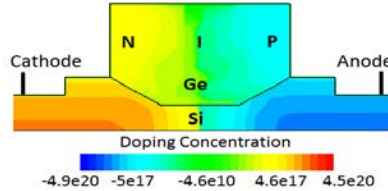
Q. Xu et al, nature 435(19), p03569 (2005)



# GeSi Franz Keldysh ELECTRO-ABSORPTION MODULATOR

## Advantages

- Uses existing Ge-detector technology
- Compact, optical BW > 35nm
- 3dB BW > 40GHz

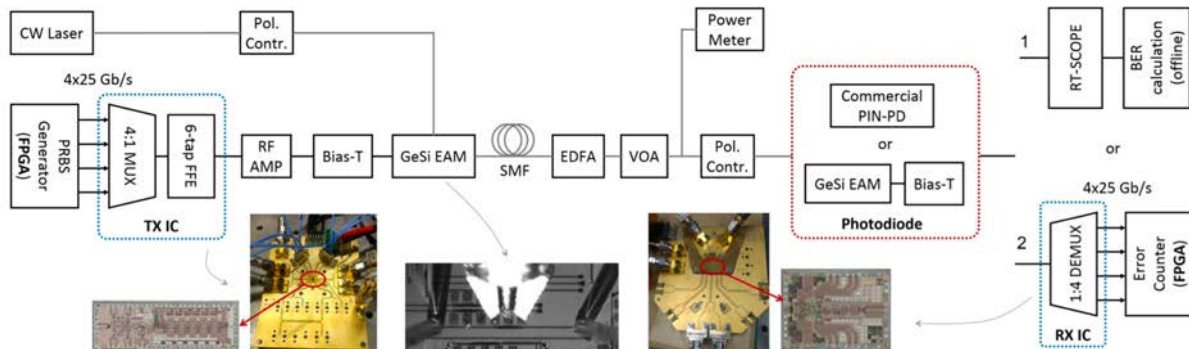


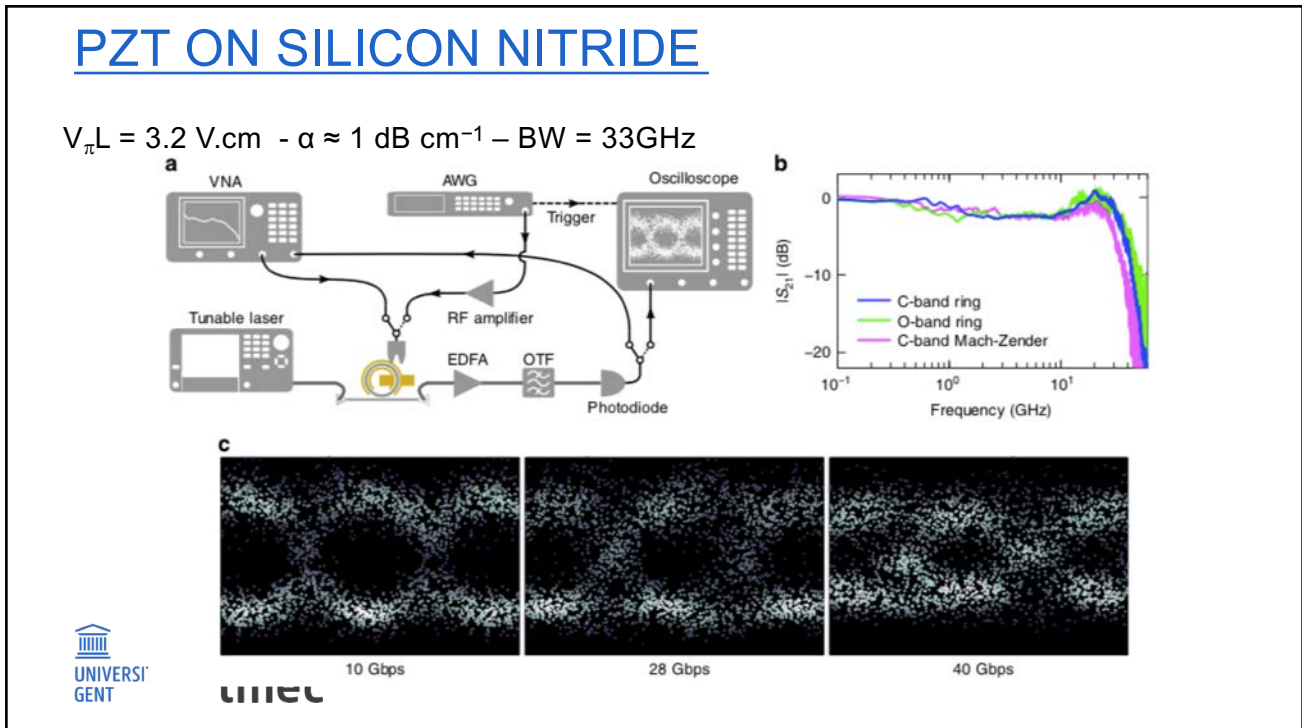
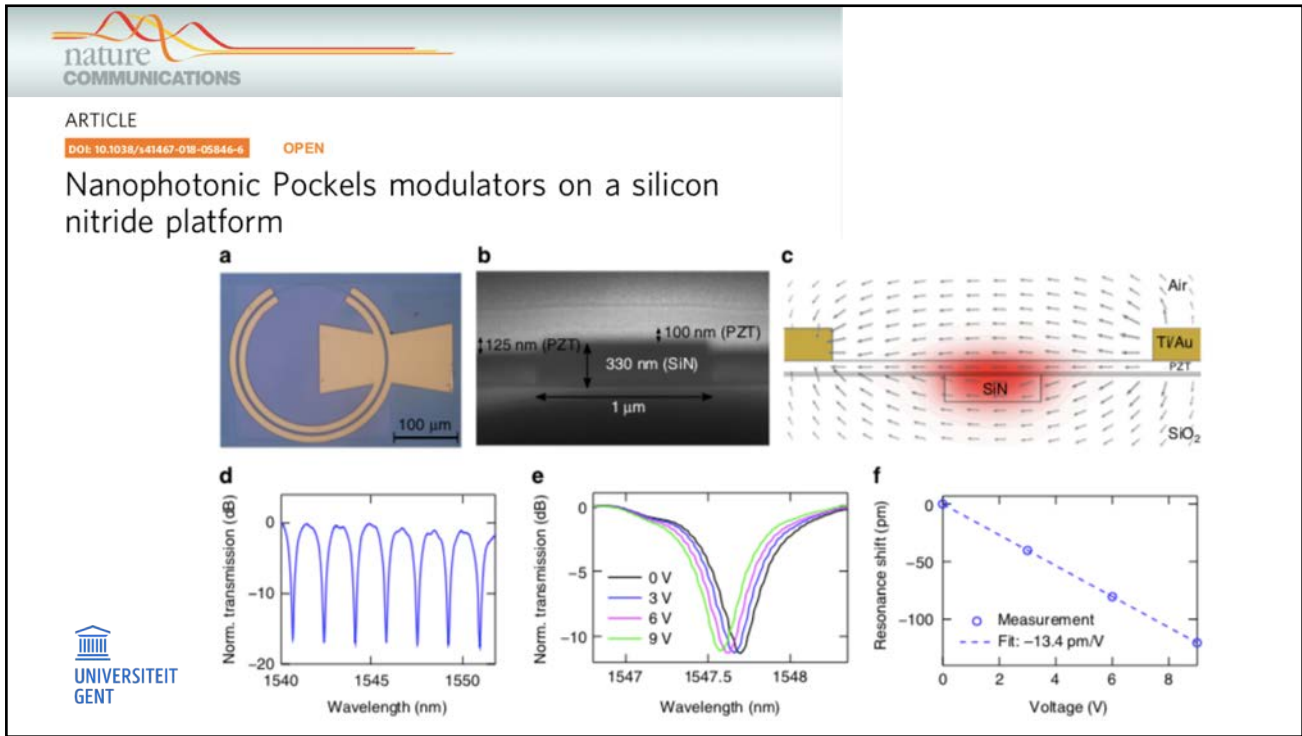
Gupta, S., et al. 50GHz Ge Waveguide Electro-Absorption Modulator Integrated in a 220nm SOI Photonics Platform. In *Optical Fiber Communication Conference* (Vol. 1, pp. 5-7) 2015.

## RESEARCH ULTRA-HIGH-SPEED COMMUNICATION

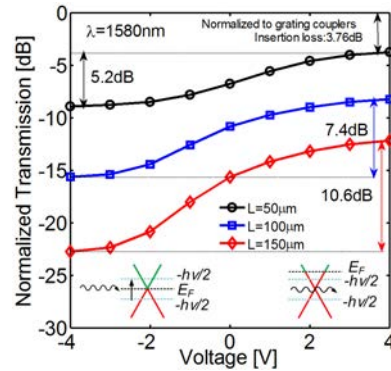
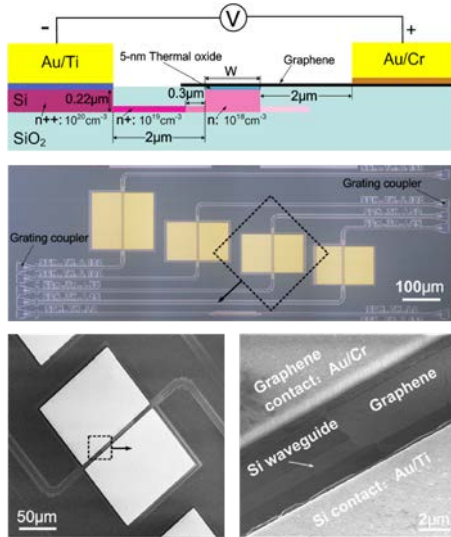
# ELECTRONIC-PHOTONIC CO-INTEGRATION

- Co-design and co-integration of electronic ICs and photonic ICs for advanced TxRx (100G per wavelength & polarization)





# GRAPHENE MODULATOR FABRICATION



- Extinction Ratio (ER) and Insertion Loss (IL) scale with device length
- Best trade-off for 50 μm device
- Neutrality point shifted to -4 Volt
- Stable up to at least 50C

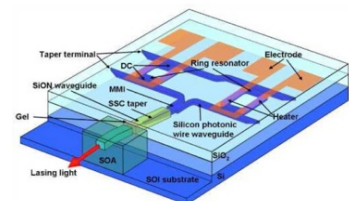


IEDM 2014, Y. Hu et al.  
imec

# LASERS FOR SILICON PHOTONICS ?

- Silicon has indirect bandgap: no light emission
- Need direct bandgap III-V semiconductors !
- Option 1: Off-chip laser
  - Most mature solution
  - Compatible with high temperature operation
  - Limited flexibility, not scalable, coupling loss
- Option 2: Flip-Chip
  - Prefabricated, pretested laser diode
  - Mature
  - Limited flexibility, limited scalability

Integration ??



Song e.a. OE 17, 14063-14068 (2009).



Luxtera "Lamp"



imec

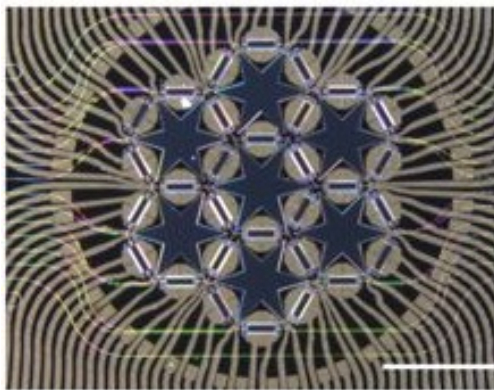
## LASERS FOR SILICON PHOTONICS: MANY OPTIONS

- Option 3: Wafer bonding (heterogeneous integration)
  - Rapidly maturing
  - Very versatile (different materials, different device structures ...)

The slide features three main sections: 'Silicon integration' showing a cross-section of a wafer being bonded to a silicon substrate; 'Silicon scale' showing a microscopic view of a silicon wafer with a grid of devices; and 'Silicon manufacturing' showing a wafer being processed in a cleanroom. The Intel Silicon Photonics logo is prominent, along with the text: 'New high-speed I/O connectivity based on photonics', 'Intel wafer-scale manufacturing with hybrid laser', and 'Platform for future high-density switch integration'. Logos for UGent and Universiteit Gent are also visible.

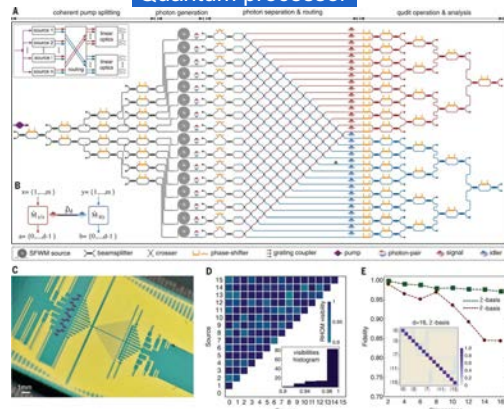
## TOWARDS LARGER DEGREE OF INTEGRATION

### Reconfigurable circuit for microwave photonics



D. Perez, Nat. Comm. 8 (2017)  
(Valencia)

### Quantum processor



J. Wang et al., Science (2018)  
(Glasgow et al)

RESEARCH INFORMATION PROCESSING & COMPUTING

## PROGRAMMABLE PHOTONIC INTEGRATED CIRCUITS

Develop general-purpose photonic ICs

- Mesh topologies (MZI, rings, lateral leakage)
- Distributed phase tuners and power monitors
- Scalable control algorithms

software  
Electrical Wiring  
In-circuit Monitors  
Outputs Monitors  
heaters  
In 1  
In 2  
In 3  
In 4

GHENT UNIVERSITY imec A. Ribeiro, Optica 3(12) (2016) 44

## PLASMONICS FOR SCALING DOWN BUILDING BLOCKS ?

a  
Au SiO<sub>2</sub>  $\lambda = \lambda_{res}$   
SPPs  $\lambda_r = \lambda_{res}$   
Photonic mode  
1  $\mu$ m

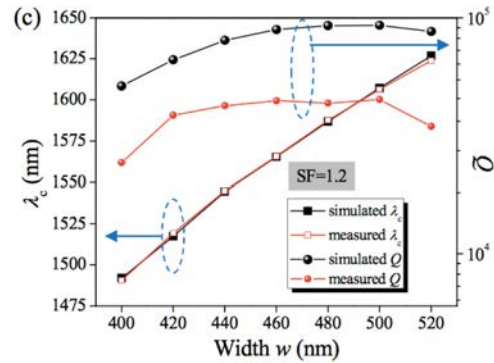
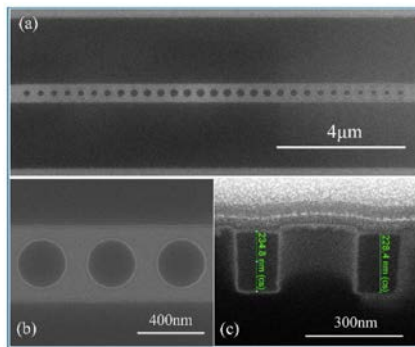
b  
Au  
Radius R  
 $d_{Au-Si} \approx 70$  nm  
Buried Si-WG  
 $w_{slot} = 70$  nm  
Pt contrast

c  
Transmittance (dB)  
Wavelength ( $\mu$ m)  
ER  $\approx 10$  dB  
Q  $\approx 30$   
IL  $\approx 2.5$  dB  
— R = 1,030 nm  
— R = 1,080 nm

Leuthold group, Nature, 556: 483-486 (ETHZ)

UNIVERSITEIT GENT imec 45

## PHOTONIC CRYSTAL DEVICES



### Photonic wire cavities fabricated using 300nm immersion litho

- Oxide cladding
- Very good match simulator vs. design, on-par with state-of-art ebeam ( $Q > 1E6$ )
- Very good uniformity over wafer
- Starting point for active devices (e.g. slow light modulators, switches ...)

## SILICON PHOTONICS – SUMMARY

- Silicon Photonics rapidly maturing:
  - All basic building blocks developed
  - Widely available from commercial foundries and through multi-project wafer services
- Current research focusses on:
  - Integration with new materials for enhancing functionality
  - Exploiting large scale integration for new applications
- Perfect match with EU-FET SPICE objectives !

GROUP



## ACKNOWLEDGMENTS – ALL GROUP MEMBERS



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FACULTEIT INGENIEURSWETENSCHAPPEN  
EN ARCHITECTUUR

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